Nanopackaging Errata

Chapter 4

Figure 4.7 (change $\lambda$)

Fig 4.14 caption: “The contours indicate the damage value in the cohesive zone elements: a black color corresponds to a value of 1.00, i.e. a crack.”

Below Equation 4.12: If $\Lambda \ll a$, 

Chapter 5

Page 99 Correct equation is: $\frac{X^m}{\rho^m} = A(T)t$

Chapter 10

Page 204 First half of first sentence in Section 10.3.4 is missing

Sumitomo Electric recently developed a new-concept ACF using nickel nano particles with a straight-chain-like structure as conductive fillers [54].
Chapter 20
Page 451  Correct figure is:

Fig. 20.4. FIB dissections of intercalated wire decorated surfaces (all gold), using flip-chip bonding principle. Bonding at ambient temperature with pressure as indicated. A: Close-up for 100 MPa sample. B: Intergrain diffusion and contact formation after annealing. All scale bars: 1 µm.

Chapter 22
Page 498  Correct figure is:

Fig. 22.8 Sketch of a typical organic flip chip package substrate.
Nanopackaging
Nanotechnologies and Electronics Packaging
Morris, J.E. (Ed.)
2008, XXI, 543 p., Hardcover